MOSFET (MISFET, IGFET)

ELEC 424
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Field Effect Transistors

- Proposed in the 1930's by Lilienfeld
 - Not practical because of role of surface defects/states
- Bardeen and Brattain were trying to demonstrate an FET when they serendipitously invented the point contact bipolar transistor.
 - Schockley extended the FET concept to the BJT
- First MOSFET finally happened in 1960

Bipolar vs Unipolar

- P-N Junction Dominate Features
 - Minority carrier injection at forward bias
 - Depletion width modulation at reverse bias
- Bipolar devices rely primarily on minority carrier injection across the narrow base region.
- Both hole and electron current matter, so they are called BIPOLAR devices.
- Junction FETs rely primarily on reverse bias to control channel width, and subsequently majority carrier current.
- FETs are sometimes called UNIPOLAR devices.

Similar but Different

- BJTs and FETs
 - Both three terminal devices
 - Current through two terminals is regulated by the third
- BUT
 - Base current controls emitter/collector current in BJTs
 - Gate voltage controls source/drain current in FETs

What Transistors Do

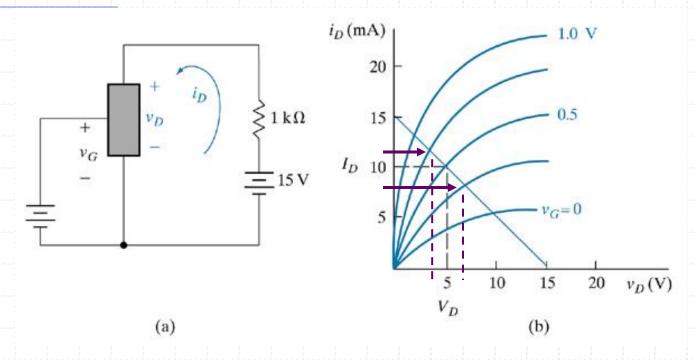
Amplify

 The electrical character of the source/drain or emitter/collector is a reflection of the character of the gate or base, but increased or decreased by a gain factor.

Switch

 Source/drain or emitter/collector current can be turned on or off by applying the proper signal to the gate or base.

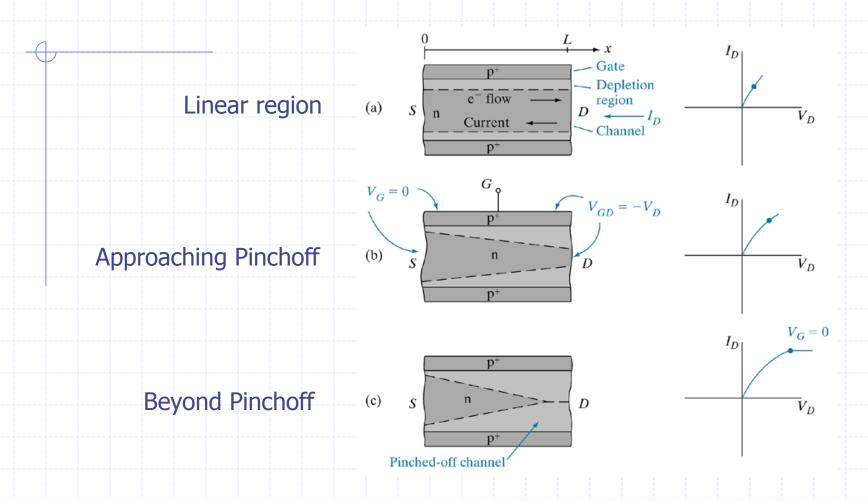
Amplification



If V_G is increased or decreased by 0.25 V, V_D will increase or decrease by ~2 volts.

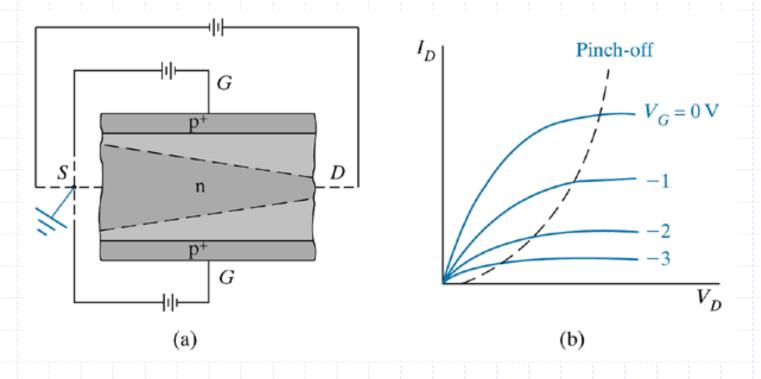
Gain =
$$V_{out}/V_{in}$$
 = 8.

JFET Operating Regions



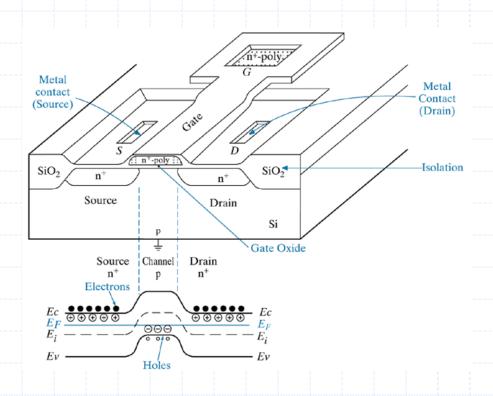
Source is the region from which the majority carriers flow. They flow to the *Drain*.

Family of Curves



 V_G determines the operating curve V_D determines the region (linear, approaching saturation, pinch-off) of operation.

MOSFET Band Diagram



Equilibrium

Invariant Fermi level bends the p-type valence band up, creating an energy barrier to electron/hole flow.

Positive Gate Voltage flattens the barrier

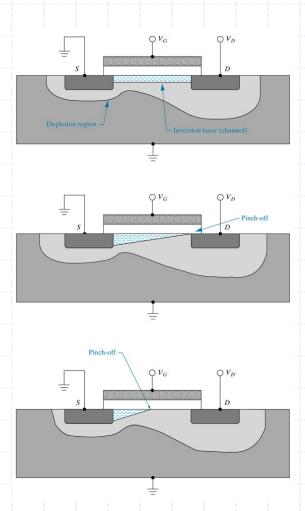
At V_T (threshold voltage)
Allows current to flow with proper source to drain bias

N-Channel MOSFET Operating Regions

Linear Region $V_G > V_T$ and $V_D < (V_G - V_T)$

Saturation onset $V_G > V_T$ and $V_D = (V_G - V_T)$

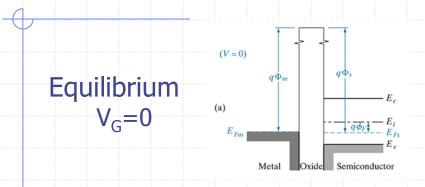
Strong Saturation $V_G > V_T$ and $V_D > (V_G - V_T)$



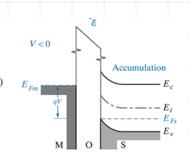
How to Build a MOSFET

http://microscopy.fsu.edu/electromag/java/transistor/index.html

N-Channel Formation in P type Material

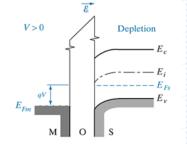


Accumulation $V_G < 0$, attracts holes to surface region



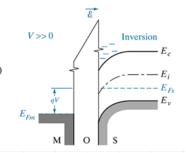
(M)etal = gate(O)xide = gate oxide(S)emiconductor = p-type

Depletion V_G>0, repels holes from surface region

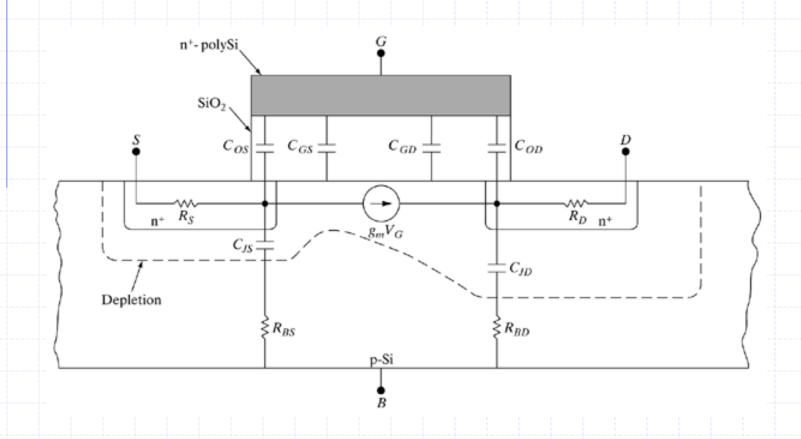


Inversion

V_G>>0, attracts electrons to surface region, making it "N type"



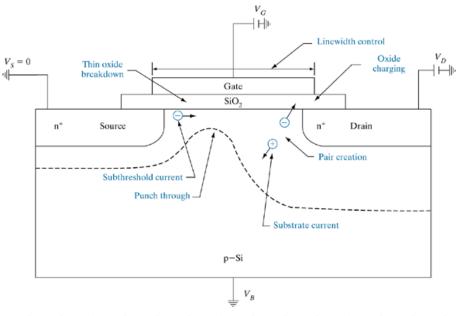
MOSFET Equivalent Circuit



MOSFET Short-Channel Effects

Shorter channels incur higher electric fields and current densities.

- Charge accumulates within the gate oxide due to hot carrier generation
- Unwanted (leakage) current flows due to punchtrough from the source to the drain
- Devices fail catastophically due to thin gate oxide breakdown (rupture)



Threshold Shift due to Hot Carriers

"Hot" electrons are
"trapped" in the gate
dielectric, imparting a
permanent charge and
subsequent threshold shift,
as shown in these before
and after I-V curves.

